Paul Conway

List of Publications by Year in descending order

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224	2,661	257450	289244
papers	citations	24 h-index	40 g-index

228	228	228	2276
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	Comparison of Selective Laser Melted Commercially Pure Titanium Sheetâ€Based Triply Periodic Minimal Surfaces and Trabecularâ€Like Strutâ€Based Scaffolds for Tissue Engineering. Advanced Engineering Materials, 2022, 24, 2100527.	3.5	7
2	Comparison of Selective Laser Melted Commercially Pure Titanium Sheetâ€Based Triply Periodic Minimal Surfaces and Trabecularâ€Like Strutâ€Based Scaffolds for Tissue Engineering. Advanced Engineering Materials, 2022, 24, .	3.5	3
3	Personalised Controller Strategies for Next Generation Intelligent Adaptive Electric Bicycles. IEEE Transactions on Intelligent Transportation Systems, 2021, 22, 7814-7825.	8.0	4
4	Enhanced interfacial adhesion and mechanical performance of lightweight polyurethane foam reinforced with a low content of aligned magnetised short carbon fibres. Composite Interfaces, 2021, 28, 309-328.	2.3	2
5	Countermovement jump performance in elite male and female sprinters and high jumpers. Proceedings of the Institution of Mechanical Engineers, Part P: Journal of Sports Engineering and Technology, 2021, 235, 131-138.	0.7	8
6	The impact of multimodal pore size considered independently from porosity on mechanical performance and osteogenic behaviour of titanium scaffolds. Materials Science and Engineering C, 2021, 124, 112026.	7.3	15
7	The Effect of Energy Density and Nb Content on the Microstructure and Mechanical Properties of Selective Laser Melted Ti-(10-30 wt.%) Nb. Journal of Materials Engineering and Performance, 2021, 30, 8771-8783.	2.5	9
8	In-silico design and experimental validation of TiNbTaZrMoSn to assess accuracy of mechanical and biocompatibility predictive models. Journal of the Mechanical Behavior of Biomedical Materials, 2021, 124, 104858.	3.1	3
9	Microstructure and Mechanical Reliability Issues of TSV. Springer Series in Advanced Microelectronics, 2021, , 71-105.	0.3	3
10	Atomic Scale Kinetics of TSV Protrusion. Springer Series in Advanced Microelectronics, 2021, , 131-155.	0.3	0
11	Comparison of in-sight and handheld navigation devices toward supporting industry 4.0 supply chains: First and last mile deliveries at the human level. Applied Ergonomics, 2020, 82, 102928.	3.1	15
12	An interoperable semantic service toolset with domain ontology for automated decision support in the end-of-life domain. Future Generation Computer Systems, 2020, 112, 848-858.	7.5	5
13	Physico-chemical characterisation of Ti-Nb-Sn alloys surfaces and their osteogenic properties. Surface and Coatings Technology, 2020, 403, 126439.	4.8	5
14	Addition of Sn to TiNb alloys to improve mechanical performance and surface properties conducive to enhanced cell activity. Materials Science and Engineering C, 2020, 115, 110839.	7.3	8
15	Processing-Structure-Protrusion Relationship of 3-D Cu TSVs: Control at the Atomic Scale. IEEE Journal of the Electron Devices Society, 2019, 7, 1270-1276.	2.1	6
16	An industrial evaluation of an Industry 4.0 reference architecture demonstrating the need for the inclusion of security and human components. Computers in Industry, 2019, 108, 37-44.	9.9	57
17	Cyber-Physical Systems in the re-use, refurbishment and recycling ofÂused Electrical and Electronic Equipment. Journal of Cleaner Production, 2018, 170, 351-361.	9.3	28
18	Protrusion of Cu-TSV under different strain states. , 2018, , .		0

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19	Microstructural and Reliability Issues of TSV. Springer Series in Advanced Microelectronics, 2017, , 71-99.	0.3	5
20	The effect of pore size and porosity on mechanical properties and biological response of porous titanium scaffolds. Materials Science and Engineering C, 2017, 77, 219-228.	7.3	132
21	Secure Document and Asset Tracking. Journal of Communications Software and Systems, 2017, 9, 24.	0.8	2
22	Aerosol-assisted fabrication of tin-doped indium oxide ceramic thin films from nanoparticle suspensions. Journal of Materials Chemistry C, 2016, 4, 5739-5746.	5.5	8
23	An atomistic study of copper extrusion in through-silicon-via using phase field crystal models. , 2016, , .		2
24	Cost estimation for remanufacture with limited and uncertain information using case based reasoning. Journal of Remanufacturing, 2015, 5, 1.	2.7	10
25	A wavelet analysis on digital microstructure in microbumps. , 2015, , .		0
26	Performance measurement and KPIs for remanufacturing. Journal of Remanufacturing, 2015, 5, 1.	2.7	28
27	Digital transformations and the archival nature of surrogates. Archival Science, 2015, 15, 51-69.	1.4	34
28	Automated cycling ergometer with built-in ability to produce resistance profiles. , 2014, , .		1
29	Sensor-enabled PCBs to aid right first time manufacture through defect prediction. , 2014, , .		0
30	Evaluating the optimal location for embedded accelerometers using experimentally validated computer algorithms. , 2014, , .		0
31	Assessing wireless inertia measurement units for monitoring athletics sprint performance. , 2014, , .		3
32	Effects of the microstructure of copper through-silicon vias on their thermally induced linear elastic mechanical behavior. Electronic Materials Letters, 2014, 10, 281-292.	2.2	15
33	Effects of Stress and Electromigration on Microstructural Evolution in Microbumps of Three-Dimensional Integrated Circuits. IEEE Transactions on Device and Materials Reliability, 2014, 14, 995-1004.	2.0	7
34	Microstructure-based multiphysics modeling for semiconductor integration and packaging. Science Bulletin, 2014, 59, 1696-1708.	1.7	2
35	Model based Automated Cycling Ergometer. Procedia Engineering, 2014, 72, 180-185.	1.2	1
36	A Method for Quantification of the Effects of Size and Geometry on the Microstructure of Miniature Interconnects. Journal of Electronic Materials, 2014, 43, 618-629.	2.2	3

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37	Design and Implementation of an Integrated Performance Monitoring Tool for Swimming to Extract Stroke Information at Real Time. IEEE Transactions on Human-Machine Systems, 2013, 43, 199-213.	3.5	35
38	Patterning of electroless copper deposition on low temperature co-fired ceramic. , 2013, , .		0
39	Size and geometry effects on microstructural evolution in Sn microbumps during isothermal aging. , 2013, , .		1
40	Linkages Between Microstructure and Mechanical Properties of Ultrafine Interconnects. Journal of Electronic Materials, 2013, 42, 263-271.	2.2	2
41	Kinetic Monte Carlo simulation of the electrodeposition of polycrystalline copper: Effects of substrates and deposition parameters on the microstructure of deposits. Electrochimica Acta, 2013, 97, 132-142.	5.2	15
42	Development of a wireless sensor network for use as an automated system for monitoring swimming starts. Proceedings of the Institution of Mechanical Engineers, Part P: Journal of Sports Engineering and Technology, 2013, 227, 184-195.	0.7	5
43	Multiscale Microstructures and Microstructural Effects on the Reliability of Microbumps in Three-Dimensional Integration. Materials, 2013, 6, 4707-4736.	2.9	0
44	Preserving Imperfection: Assessing the Incidence of Digital Imaging Error in HathiTrust. Preservation, Digital Technology and Culture, 2013, 42, 17-30.	0.4	13
45	The categorisation of swimming start performance with reference to force generation on the main block and footrest components of the Omega OSB11 start blocks. Journal of Sports Sciences, 2013, 31, 468-478.	2.0	35
46	A Novel Instrumented Cycle Ergometer with Automated In-Situ Capabilities. , 2013, , .		3
47	A wireless sensor system for monitoring the performance of a swimmerâ€™s tumble turn. Proceedings of the Institution of Mechanical Engineers, Part P: Journal of Sports Engineering and Technology, 2013, 227, 161-171.	0.7	4
48	Sustainable production in the UK: a tool to support printed circuit assembly (PCA) manufacturing. International Journal of Computer Integrated Manufacturing, 2013, 26, 346-364.	4.6	8
49	Characterisation of the Mechanical Bond Strength for Copper on Glass Plating Applications. , 2013, , 303-320.		0
50	A multiâ€electrode array (MEA) biochip with excimer laserâ€produced microâ€well features. Circuit World, 2012, 38, 30-37.	0.9	1
51	Integrated inâ€plane mirror and multimode waveguide fabrication using 248 nm excimer laser ablation for optical interconnects on PCBs. Circuit World, 2012, 38, 59-63.	0.9	0
52	Information structure required for life-cycle monitoring of electronic products. Proceedings of the Institution of Mechanical Engineers, Part B: Journal of Engineering Manufacture, 2012, 226, 1612-1627.	2.4	6
53	Image processing algorithms to extract swimming tumble turn signatures in real-time. , 2012, , .		1
54	Product life cycle information management in the electronics supply chain. Proceedings of the Institution of Mechanical Engineers, Part B: Journal of Engineering Manufacture, 2012, 226, 1388-1400.	2.4	15

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55	Characterizing the swimming tumble turn using acceleration data. Proceedings of the Institution of Mechanical Engineers, Part P: Journal of Sports Engineering and Technology, 2012, 226, 3-15.	0.7	14
56	Excimer laser machining of microvias in glass substrates for the manufacture of high density interconnects. Applied Physics B: Lasers and Optics, 2012, 108, 137-147.	2.2	4
57	Development of a Novel System for Monitoring Strength and Conditioning in Elite Athletes. Procedia Engineering, 2012, 34, 496-501.	1.2	5
58	Swimming Turn Technique Optimisation by Real-Time Measurement of Foot Pressure and Position. Procedia Engineering, 2012, 34, 586-591.	1.2	9
59	The Effect of Knee Angle on Force Production, in Swimming Starts, using the OSB11 Block. Procedia Engineering, 2012, 34, 801-806.	1.2	11
60	Effects of microstructure on vacancy and stress distributions in micro joints under current stressing. , 2012, , .		0
61	Adhesion improvement of electroless copper (Cu) thin films deposited on Low Temperature Co-fired Ceramics (LTCC). , 2012, , .		0
62	CO2 laser micromachining of optical waveguides for interconnection on circuit boards. Optics and Lasers in Engineering, 2012, 50, 1752-1756.	3.8	13
63	An atomistic scale study on solidification in ultrafine interconnects. , 2012, , .		0
64	Evolution of microstructure and electrical conductivity of electroless copper deposits on a glass substrate. Thin Solid Films, 2012, 520, 6095-6099.	1.8	49
65	A Multi-sensor System for Monitoring the Performance of Elite Swimmers. Communications in Computer and Information Science, 2012, , 350-362.	0.5	6
66	Effect of microstructure on thermal-mechanical stress in 3D copper TSV structures. , 2011, , .		2
67	Development of a wireless sensor network for embedded monitoring of human motion in a Harsh environment. , 2011, , .		6
68	Development of an automated cycle ergometer. Procedia Engineering, 2011, 13, 69-74.	1.2	1
69	Development of a pressure sensor for swimming turns. Procedia Engineering, 2011, 13, 126-132.	1.2	8
70	The effect of start block configuration and swimmer kinematics on starting performance in elite swimmers using the Omega OSB11 block. Procedia Engineering, 2011, 13, 141-147.	1.2	9
71	A generalized computational interface for combined thermodynamic and kinetic modeling. Calphad: Computer Coupling of Phase Diagrams and Thermochemistry, 2011, 35, 391-395.	1.6	8
72	Fabrication of Polymer Waveguides by Laser Ablation Using a 355 nm Wavelength Nd:YAG Laser. Journal of Lightwave Technology, 2011, 29, 3566-3576.	4.6	21

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73	Root cause analysis support for quality improvement in electronics manufacturing. Assembly Automation, 2011, 31, 38-46.	1.7	7
74	Archival quality and long-term preservation: a research framework for validating the usefulness of digital surrogates. Archival Science, 2011, 11, 293-309.	1.4	13
75	Embedded programming and real-time signal processing of swimming strokes. Sports Engineering, 2011, 14, 1-14.	1.1	54
76	The Evolution of Pdâ•Sn Catalytic Surfaces in Electroless Copper Deposition. Journal of the Electrochemical Society, 2011, 158, D172.	2.9	38
77	Combining business process and failure modelling to increase yield in electronics manufacturing. Proceedings of the Institution of Mechanical Engineers, Part B: Journal of Engineering Manufacture, 2011, 225, 264-281.	2.4	1
78	A database system for decision support in low-volume electronics assembly. Proceedings of the Institution of Mechanical Engineers, Part B: Journal of Engineering Manufacture, 2011, 225, 1411-1430.	2.4	5
79	Design and implementation of a user-centric swimming performance monitoring tool. Proceedings of the Institution of Mechanical Engineers, Part P: Journal of Sports Engineering and Technology, 2011, 225, 213-229.	0.7	7
80	Implementing PREMIS: a case study of the Florida Digital Archive. Library Hi Tech, 2010, 28, 273-289.	5.1	5
81	Integrated optical and electronic interconnect PCB manufacturing research. Circuit World, 2010, 36, 5-19.	0.9	40
82	New lifecycle monitoring system for electronic manufacturing with embedded wireless components. Circuit World, 2010, 36, 33-39.	0.9	12
83	Dynamic signature for tumble turn performance in swimming. Procedia Engineering, 2010, 2, 3391-3396.	1.2	15
84	Formation of Ag3Sn plates in SnAgCu solder bumps. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2010, 527, 2588-2591.	5.6	31
85	Low frequency induction heating for the sealing of plastic microfluidic systems. Microfluidics and Nanofluidics, 2010, 9, 243-252.	2.2	20
86	Development of a real time system for monitoring of swimming performance. Procedia Engineering, 2010, 2, 2707-2712.	1.2	23
87	Design of an end-user centric information interface from data-rich performance analysis tools in elite swimming. Procedia Engineering, 2010, 2, 2713-2719.	1.2	3
88	The development of an inexpensive passive marker system for the analysis of starts and turns in swimming. Procedia Engineering, 2010, 2, 2727-2733.	1.2	11
89	Design and construction of large-area flexible printed-circuit automotive electrical interconnection harnesses. Proceedings of the Institution of Mechanical Engineers, Part D: Journal of Automobile Engineering, 2010, 224, 785-797.	1.9	4
90	An integrated approach to Design for Quality (DfQ) in the high value added printed circuit assembly (PCA) manufacturing: A pilot tool. , 2010, , .		0

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91	Deployment of a reflow process model to support quality and reliability in PCA manufacturing. , 2010, , .		0
92	Fabrication of a Polymeric Optical Waveguide-On-Flex Using Electrostatic-Induced Lithography. IEEE Photonics Technology Letters, 2010, 22, 957-959.	2.5	8
93	Preservation in the Age of Google: Digitization, Digital Preservation, and Dilemmas. Library Quarterly, 2010, 80, 61-79.	0.8	79
94	A systems integration perspective to manufacturing modelling and simulation. , 2010, , .		2
95	Polymer bonding by induction heating for microfluidic applications. , 2010, , .		2
96	Integrated simulation tool for quality support in the low-volume high-complexity electronics manufacturing domain. International Journal of Production Research, 2010, 48, 45-68.	7.5	9
97	Modes of Seeing: Digitized Photographic Archives and the Experienced User. American Archivist, 2010, 73, 425-462.	0.1	18
98	Integrated modelling for simulation in the electronics manufacturing domain. , 2009, , .		4
99	Initial formation of CuSn intermetallic compounds between molten SnAgCu solder and Cu substrate. Scripta Materialia, 2009, 60, 333-335.	5.2	53
100	Formation of Sn dendrites and SnAg eutectics in a SnAgCu solder. Scripta Materialia, 2009, 61, 682-685.	5.2	21
101	Modeling of interfacial intermetallic compounds in the application of very fine lead-free solder interconnections. Microsystem Technologies, 2009, 15, 101-107.	2.0	11
102	Heterogeneous Intragranular Inelastic Behavior of a Sn-Ag-Cu Alloy. Journal of Electronic Materials, 2009, 38, 2429-2435.	2.2	2
103	Kinetic Monte Carlo simulation of electrodeposition of polycrystalline Cu. Electrochemistry Communications, 2009, 11, 2207-2211.	4.7	9
104	Kinetic Monte Carlo simulation of kinetically limited copper electrocrystallization on an atomically even surface. Electrochimica Acta, 2009, 54, 6941-6948.	5.2	12
105	Surface characterisation of plasma treated flexible substrates for waveguide-on-flex application. Surface and Coatings Technology, 2009, 203, 3741-3749.	4.8	6
106	Polymer optical waveguide fabrication using laser ablation. , 2009, , .		12
107	Productionisation issues for commercialisation of microfluidic based devices. Sensor Review, 2009, 29, 349-354.	1.8	6
108	Growth and recrystallization of electroplated copper columns. , 2009, , .		0

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109	Packaging of Microfluidic Devices for Fluid Interconnection Using Thermoplastics. Journal of Microelectromechanical Systems, 2009, 18, 354-362.	2.5	6
110	Enabling Technologies for Robust Performance Monitoring (P10). , 2009, , 45-54.		1
111	Evolution of CuSn intermetallics between molten SnAgCu solder and Cu substrate. Acta Materialia, 2008, 56, 4291-4297.	7.9	111
112	Plastic Packaging Using Low Frequency Induction Heating (LFIH) For Microsystems. , 2008, , .		3
113	Packaging of polymer based microfluidic systems using low frequency induction heating (LFIH). , 2008, , .		3
114	A computational interface for thermodynamic calculations software MTDATA. Calphad: Computer Coupling of Phase Diagrams and Thermochemistry, 2008, 32, 129-134.	1.6	11
115	Mesomechanical modelling of SnAgCu solder joints in flip chip. Computational Materials Science, 2008, 43, 199-211.	3.0	18
116	Corrosion characterization of tinâ€“lead and lead free solders in 3.5wt.% NaCl solution. Corrosion Science, 2008, 50, 995-1004.	6.6	195
117	An investigation of electroless copper films deposited on glass. , 2008, , .		2
118	Growth mechanism of copper column by electrodeposition for electronic interconnections. , 2008, , .		0
119	Characterization of printed solder paste excess and bridge related defects. , 2008, , .		6
120	Glass as a Substrate for High Density Electrical Interconnect. , 2008, , .		12
121	Modeling the digital content landscape in universities. Library Hi Tech, 2008, 26, 342-354.	5.1	20
122	Integration issues in the development of a modelling and simulation tool for low volume high-complexity electronics manufacture. , 2008, , .		0
123	Virtual prototyping of flexible soldering cells for electronic manufacture. Proceedings of the Institution of Mechanical Engineers, Part B: Journal of Engineering Manufacture, 2008, 222, 711-722.	2.4	2
124	Evaluating a new flexible soldering system for electronics small and medium enterprises. Proceedings of the Institution of Mechanical Engineers, Part B: Journal of Engineering Manufacture, 2008, 222, 273-283.	2.4	5
125	Investigation of the Adhesion of Electroless Copper to Glass Substrates. Materials Research Society Symposia Proceedings, 2008, 1113, 1.	0.1	0
126	Interfacial Reaction Between Molten Sn-Bi Based Solders and Electroless Ni-P Coatings for Liquid Solder Interconnects. IEEE Transactions on Components and Packaging Technologies, 2008, 31, 574-585.	1.3	5

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127	Variation in the line stability of an inkjet printed optical waveguide-applicable material. , 2008, , .		14
128	The effect of surface modification on adhesion of polymer waveguide on flexible substrate. , 2008, , .		1
129	Controlling Interfacial Interpenetration of Polymer Waveguide Deposited on Plasma Treated Flexible Substrate. , 2008, , .		1
130	Role of CAD Post-Processing in a Quality Tool for Low Volume High-Complexity Electronics Manufacture. , 2008, , .		0
131	A simulation module for supporting the manufacture of high value added electronics manufacturing. , 2008, , .		2
132	Innovative Optical and Electronic Interconnect Printed Circuit Board Manufacturing research. , 2008, , .		5
133	Integrated optical and electronic interconnect printed circuit board manufacturing. Circuit World, 2008, 34, 21-26.	0.9	10
134	Excimer laser micromachining of glass substrates. , 2008, , .		1
135	Reliability of Fine Pitch Snâ€“3.8Agâ€“0.7Cu Flip Chip Solder Joints With Different Connection Pads on PCB. Journal of Electronic Packaging, Transactions of the ASME, 2008, 130, .	1.8	2
136	A Review on 3D Integrated Approaches in Multimode Optical Polymeric Waveguide Fabrication. , 2007, , .		3
137	Crystallographic Features of Copper Column Growth by Reversible Pulse Current Electrodeposition. , 2007, , .		2
138	Adhesion of Precision Welded Lead-Free Electrical Interconnects Formed by Molten Droplet Deposition. Proceedings of the Institution of Mechanical Engineers, Part B: Journal of Engineering Manufacture, 2007, 221, 303-315.	2.4	0
139	Challenges in the manufacture of glass substrates for electrical and optical interconnect. Circuit World, 2007, 33, 22-30.	0.9	8
140	Micromechanical modelling of SnAgCu solder joint under cyclic loading: Effect of grain orientation. Computational Materials Science, 2007, 39, 187-197.	3.0	39
141	Complex Low Volume Electronics Simulation Tool to Improve Yield and Reliability. Electronics Manufacturing Technology Symposium (IEMT), IEEE/CPMT International, 2007, , .	0.0	4
142	Crystallographic Structure and Mechanical Behaviour of SnAgCu Solder Interconnects under a Constant Loading Rate. , 2007, , .		3
143	Copper Deposition and Patterning for Glass Substrate Manufacture. , 2007, , .		7
144	A Modelling Framework for the Reliability of Safety Critical Electronics. , 2007, , .		0

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145	Glass Multilayer Lamination for PCB Manufacture using Pressure Assisted Low Temperature Bonding. , 2007, , .		1
146	Process Optimisation and Characterization of Excimer Laser Drilling of Microvias in Glass. , 2007, , .		11
147	Effects of plies assembling on textile composite cellular structures. Materials & Design, 2007, 28, 857-870.	5.1	10
148	Materials behaviour and intermetallics characteristics in the reaction between SnAgCu and Snâ€“Pb solder alloys. Journal of Materials Science, 2007, 42, 4076-4086.	3.7	7
149	Manufacture of a human mesenchymal stem cell population using an automated cell culture platform. Cytotechnology, 2007, 55, 31-39.	1.6	55
150	Microstructural considerations for ultrafine lead free solder joints. Microelectronics Reliability, 2007, 47, 1997-2006.	1.7	23
151	Thermal Interface Materials - A Review of the State of the Art. , 2006, , .		156
152	Integration and Packaging of Microsystems by Polymer Overmoulding. , 2006, , .		2
153	Materials and Processes Issues in Fine Pitch Eutectic Solder Flip Chip Interconnection. IEEE Transactions on Components and Packaging Technologies, 2006, 29, 869-876.	1.3	2
154	A case-based reasoning approach for low volume, high added value electronics. , 2006, , .		4
155	Novel approach to reflow oven design to control and optimise lead free soldering process. , 2006, , .		1
156	Reliability of fine pitch Sn-3.8Ag-0.7Cu flip chip solder joints with different connection pads. , 2006, , .		0
157	Flexible soldering cells for small batch productions. , 2006, , .		0
158	Mechanical Behaviour of Grains in SnAgCu Solder Joints. , 2006, , .		0
159	Modelling of Ag3Sn coarsening and its effect on creep of Snâ€“Ag eutectics. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2006, 427, 60-68.	5.6	48
160	Reliability issues in Pb-free solder joint miniaturization. Journal of Electronic Materials, 2006, 35, 1761-1772.	2.2	38
161	Microstructure and shear strength evolution of Sn-Ag-Cu solder bumps during aging at different temperatures. Journal of Electronic Materials, 2006, 35, 388-398.	2.2	26
162	Modeling the interdependence of processing and alloy composition on the evolution of microstructure in Sn-based lead-free solders in fine pitch flip chip. IEEE Transactions on Components and Packaging Technologies, 2006, 29, 98-104.	1.3	2

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163	Analysis of Stress Distribution in SnAgCu Solder Joint. Applied Mechanics and Materials, 2006, 5-6, 359-366.	0.2	4
164	Challenges in the Manufacture of Glass Substrates for Electrical and Optical Interconnect. , 2006, , .		2
165	Effect of Microstructural Characteristics of Electroless Nickel Metallisation on Solderability to Pb-Free Solder Alloys. , 2005, , 1819.		0
166	Thermo-mechanical properties and regression models of alloys: AISI 305, CK 60, CuBe2 and Laiton MS 63. Journal of Materials Processing Technology, 2005, 168, 152-163.	6.3	11
167	Characteristics of intermetallics and micromechanical properties during thermal ageing of Snâ€“Agâ€“Cu flip-chip solder interconnects. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2005, 391, 95-103.	5.6	94
168	Effect of solder bump geometry on the microstructure of Snâ€“3.5 wt% Ag on electroless nickel immersion gold during solder dipping. Journal of Materials Research, 2005, 20, 649-658.	2.6	11
169	Sub-100 micron pitch stencil printing for wafer scale bumping. , 2005, , .		1
170	Impacts of Pb-free legislation on European HDP. , 2005, , .		0
171	Solderability of electroless deposited Niâ€P coatings with Snâ€3.8Agâ€0.7Cu and Snâ€3.5Ag leadâ€free solder alloys. Circuit World, 2005, 31, 32-39.	0.9	5
172	Electromagnetic compatibility performance of large area flexible printed circuit automotive harness. Proceedings of the Institution of Mechanical Engineers, Part D: Journal of Automobile Engineering, 2004, 218, 667-673.	1.9	2
173	Analysis of the Micro-Mechanical Properties in Aged Lead-Free, Fine Pitch Flip Chip Joints. Journal of Electronic Packaging, Transactions of the ASME, 2004, 126, 359-366.	1.8	4
174	The effect of microstructural and geometrical features on the reliability of ultrafine flip chip microsolder joints. Journal of Electronic Materials, 2004, 33, 1227-1235.	2.2	16
175	Analysis of the Micro-Mechanical Properties in Aged Lead-Free, Fine Pitch Flip Chip Joints. , 2003, , .		5
176	Electroless nickel bumping of aluminum bondpads. I. Surface pretreatment and activation. IEEE Transactions on Components and Packaging Technologies, 2002, 25, 87-97.	1.3	50
177	Electroless nickel bumping of aluminum bondpads. II. Electroless nickel plating. IEEE Transactions on Components and Packaging Technologies, 2002, 25, 98-105.	1.3	20
178	Foresight Vehicle: Large Area Flexible Circuits for Automotive Applications Manufacturing Technology - A Review of Process Options. , 2002, , .		1
179	Foresight Vehicle: Specification and Acceptability Criteria for Copper-Clad Dielectric Materials Used in Large Automotive Flexible Printed Circuits. , 2002, , .		1
180	Precision high temperature lead-free solder interconnections by means of high-energy droplet deposition techniques. CIRP Annals - Manufacturing Technology, 2002, 51, 177-180.	3.6	16

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181	Investigation of a solder bumping technique for flipâ€chip interconnection. Soldering and Surface Mount Technology, 2000, 12, 7-14.	1.5	1
182	STATISTICAL OPTIMISATION OF THERMOPLASTIC INJECTION MOULDING PROCESS FOR THE ENCAPSULATION OF ELECTRONIC SUBASSEMBLY. Journal of Electronics Manufacturing, 2000, 10, 171-179.	0.4	8
183	UNDER BUMP METALLISATION OF FINE PITCH FLIP-CHIP USING ELECTROLESS NICKEL DEPOSITION. Journal of Electronics Manufacturing, 2000, 10, 161-170.	0.4	9
184	Development of a Closed-Loop Controlled Reflow Soldering Process. CIRP Annals - Manufacturing Technology, 1999, 48, 5-8.	3.6	3
185	Effective modeling of the reflow soldering process: basis, construction, and operation of a process model. IEEE Transactions on Components, Packaging and Manufacturing Technology Part C Manufacturing, 1998, 21, 126-133.	0.4	34
186	Effective modeling of the reflow soldering process: use of a modeling tool for product and process design. IEEE Transactions on Components, Packaging and Manufacturing Technology Part C Manufacturing, 1998, 21, 165-171.	0.4	14
187	A modelling tool for the thermal optimisation of the reflow soldering of printed circuit assemblies. Finite Elements in Analysis and Design, 1998, 30, 47-63.	3.2	16
188	The application of IR thermography to process monitoring and control of reflow soldering. Soldering and Surface Mount Technology, 1998, 10, 13-18.	1.5	3
189	DEVELOPMENT AND R&D CAPABILITY AT MANUFACTURING SITES: ELECTRONICS MULTINATIONALS IN SINGAPORE AND TAIWAN. Production and Operations Management, 1997, 6, 131-149.	3.8	4
190	Design and Manufacture by Foreign Electronics Multi-Nationals in Singapore and Taiwan: Product Responsibilities in a Global Environment. Proceedings of the Institution of Mechanical Engineers, Part B: Journal of Engineering Manufacture, 1996, 210, 221-231.	2.4	4
191	Experimental Investigation of the Formation of Surface Mount Solder Joints. Journal of Electronic Packaging, Transactions of the ASME, 1996, 118, 223-228.	1.8	4
192	Simulation and Interpretation of Wetting Balance Tests Using the Surface Evolver. Journal of Electronic Packaging, Transactions of the ASME, 1996, 118, 134-141.	1.8	11
193	Offshore development of electronic products. Engineering Management Journal, 1994, 4, 185.	0.0	4
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